

	Type	L #	Hits	Search Text	DBs
1	BRS	L2	388	"257"/\$.ccls. and (board substrate carrier) with (contact pad I/O) same solder and dummy	US-PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TDB
2	BRS	L3	557	"257"/\$.ccls. and (board substrate carrier) with (contact pad I/O) same solder and (dummy tack)	US-PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TDB
3	BRS	L4	241	"257"/\$.ccls. and (board substrate carrier) with (contact pad I/O) same solder and (dummy tack) with (contact pad I/O)	US-PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TDB
4	BRS	L10	95	"438"/\$.ccls. and (board substrate carrier) with (contact pad I/O) same solder and (dummy tack) with (contact pad I/O)	US-PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TDB

	Type	L #	Hits	Search Text	DBs
5	BRS	L11	43	"361"/\$.ccls. and (board substrate carrier) with (contact pad I/O) same solder and (dummy tack) with (contact pad I/O)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
6	BRS	L12	42	"29"/\$.ccls. and (board substrate carrier) with (contact pad I/O) same solder and (dummy tack) with (contact pad I/O)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B